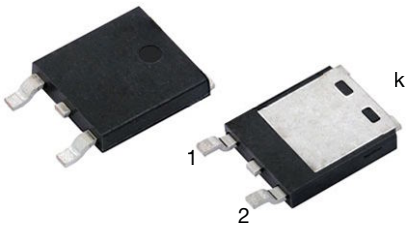
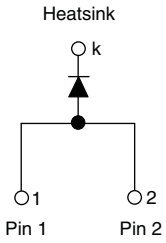
Hyperfast Rectifier, 6 A FRED Pt®

eSMP® Series



SlimDPAK (TO-252AE)



FEATURES

- Hyperfast recovery time, reduced Q_{rr} and soft recovery
- For PFC CRM / CCM operation
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

HALOGEN FREE

DESIGN SUPPORT TOOLS AVAILABLE

3D Models

TYPICAL APPLICATIONS

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters, or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating

Base PN/-M3 - halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	6 A
V_R	600 V
V_F at I_F	1.26 V
t_{rr} (typ.)	16 ns
T_J max.	175 °C
Package	SlimDPAK (TO-252AE)
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	T_C = 148 °C	6	A
Non-repetitive peak surge current	I_{FSM}	T_J = 25 °C, 10 ms sine pulse wave	70	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	I_R = 100 µA	600	-	-	V
Forward voltage	V_F	I_F = 6 A	-	1.6	2.10	
		I_F = 6 A, T_J = 150 °C	-	1.26	1.70	
Reverse leakage current	I_R	V_R = V_R rated	-	-	5	µA
		T_J = 150 °C, V_R = V_R rated	-	-	250	
Junction capacitance	C_T	V_R = 600 V	-	10	-	pF

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	I_F = 1 A, dI_F/dt = 50 A/µs, V_R = 30 V		-	22	-	ns
		I_F = 1 A, dI_F/dt = 100 A/µs, V_R = 30 V		-	16	-	
		I_F = 0.5 A, I_R = 1 A, I_{RR} = 0.25 A		-	-	28	
		T_J = 25 °C	I_F = 6 A dI_F/dt = 500 A/µs V_R = 400 V	-	28	-	
		T_J = 125 °C		-	60	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	5.5	-	A
		T_J = 125 °C		-	8.5	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	100	-	nC
		T_J = 125 °C		-	250	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-55	-	175	°C
Thermal resistance, junction to case	R_{thJC}		-	-	2.5	°C/W
Marking device		Case style SlimDPAK (TO-252AE)	6EVH06			

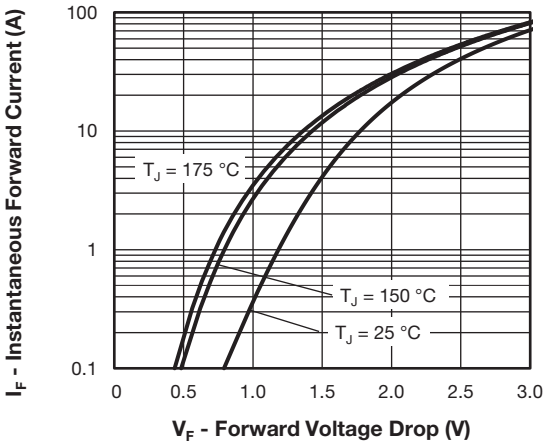


Fig. 1 - Typical Forward Voltage Drop Characteristics

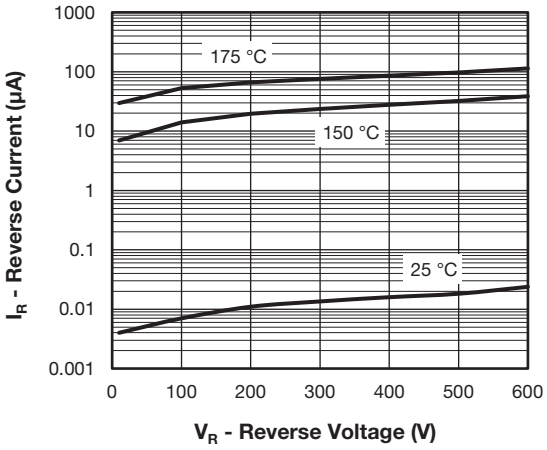


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

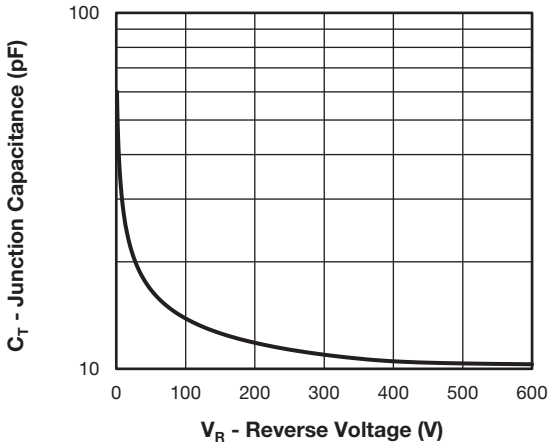


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

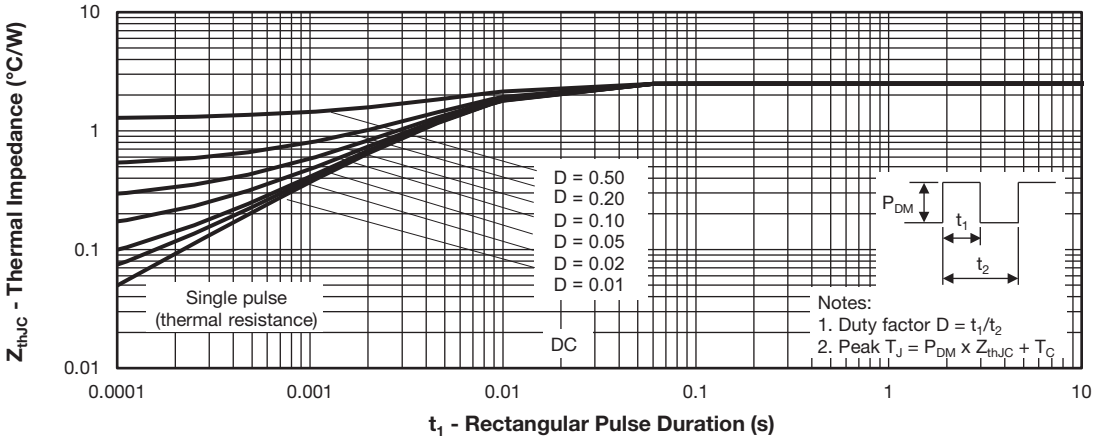


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

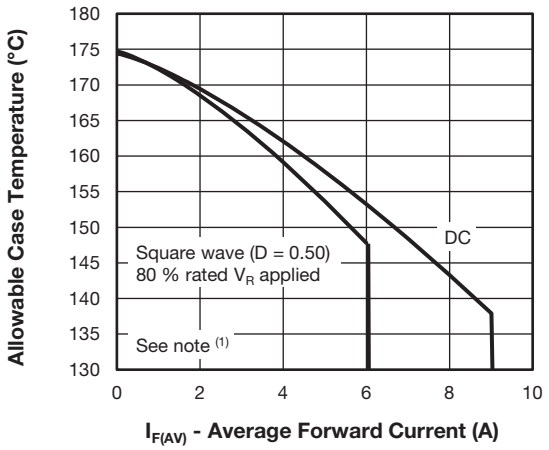


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

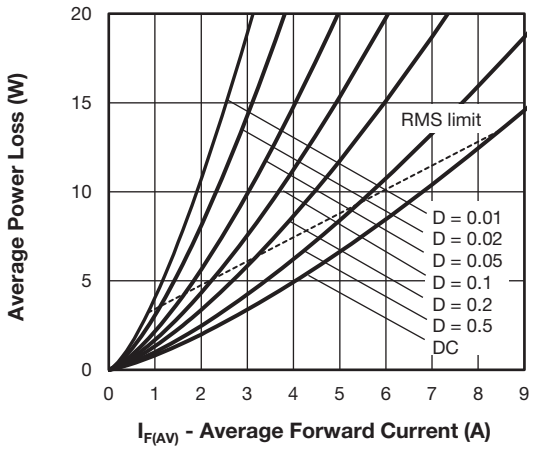


Fig. 6 - Forward Power Loss Characteristics

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 6);
Pd_{REV} = inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = rated V_R

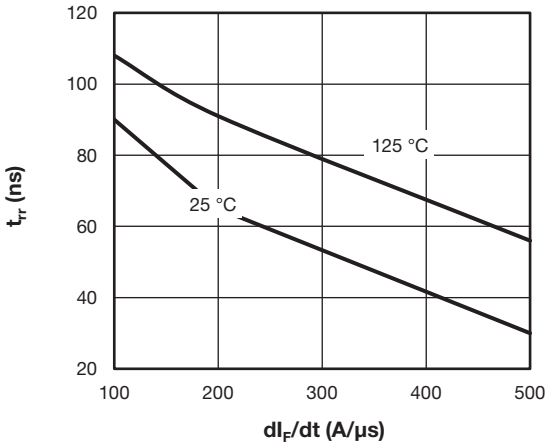


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

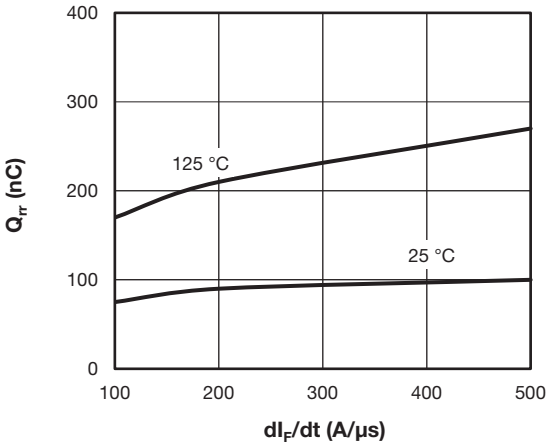
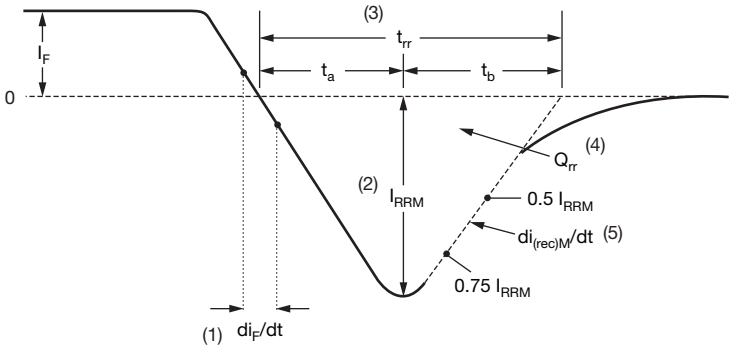


Fig. 8 - Typical Stored Charge vs. dI_F/dt



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

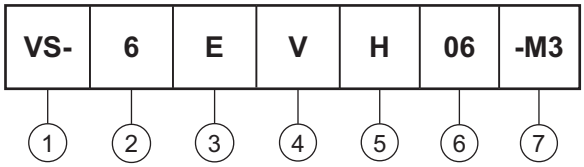
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (6 = 6 A)

3 - Circuit configuration:
E = single die

4 - V = SlimDPAK

5 - Process type:
H = hyperfast recovery

6 - Voltage code (06 = 600 V)

7 - Environmental digit:
-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

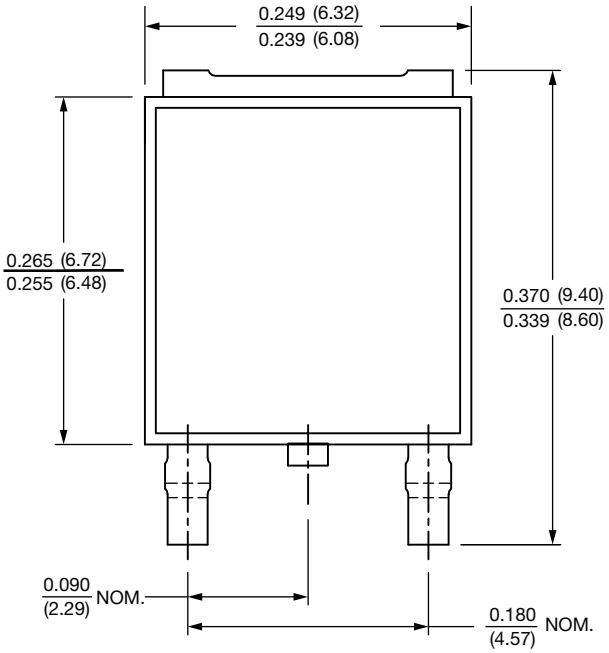
ORDERING INFORMATION (Example)				
PREFERRED P/N	**UNIT WEIGHT (g)**	**PREFERRED PACKAGE CODE**	**BASE QUANTITY**	**PACKAGING DESCRIPTION**
VS-6EVH06-M3/I	0.20	1	4500	13"diameter plastic tape and reel

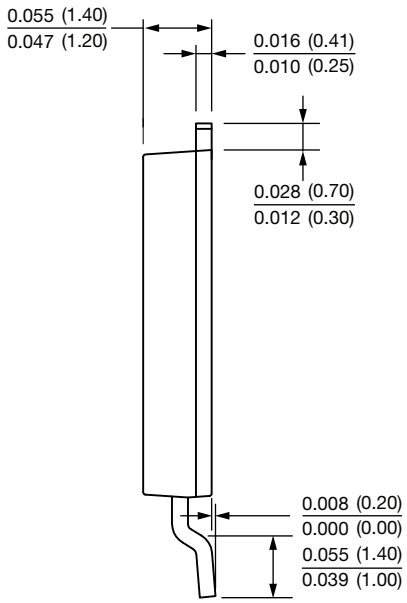
LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96081
Part marking information	www.vishay.com/doc?96085
Packaging information	www.vishay.com/doc?88869

SlimDPAK

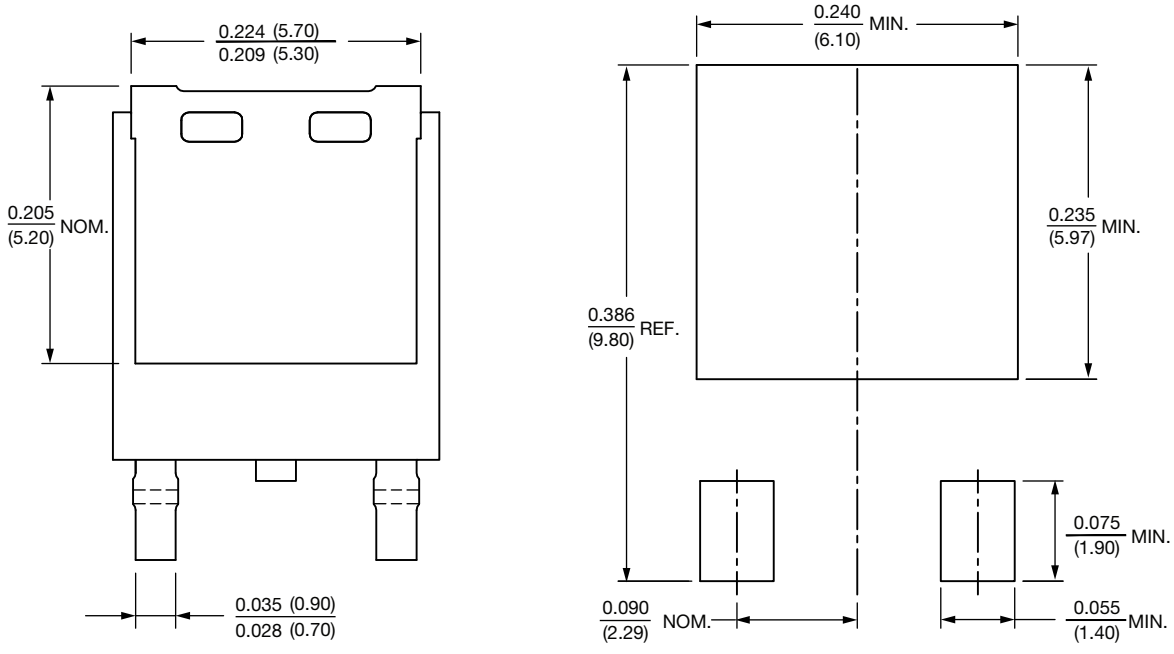
DIMENSIONS in inches (millimeters)

SlimDPAK





Mounting Pad Layout



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